



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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HIGHEST THERMAL CONDUCTIVITY COMPLIANT GAP FILLER

Tflex[™] 700 is a 5 W/mK soft gap filler thermal interface material with great thermal performance and high compliancy. The soft interface pad conforms to component topography, resulting in little or no stress on the components and mating chassis or parts.

Unique silicone and ceramic filler technology allows a combination of high compliancy and high thermal performance. Tflex[™] 700 is stable from -45°C thru 200°C and meets UL 94V0 flame rating. Naturally tacky, it requires no additional adhesive coating which inhibits thermal performance.

FEATURES AND BENEFITS

- Thermal conductivity 5.0 W/mK
- Highly compliant
- Low thermal resistance even at low pressure
- Available in thicknesses from 0.020" thru 0.200" (0.5mm thru 5.0mm)
- Naturally tacky for adhesion during assembly and transport

APPLICATIONS

- Cooling components to chassis, frame or other mating components
- Mass storage devices
- Heat pipe thermal solutions for notebook computers
- Automotive engine control
- Telecommunication hardware
- LED solid state lighting
- Power electronics
- Flat panel displays
- Audio and video components
- Computer servers and other IT infrastructure
- GPS navigation and other portable devices

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Tflex™ 700 Series Thermal Gap Filler

	Tflex™ 700	TEST METHOD
Construction	Filled Silicone Sheet	N/A
Color	Dark Grey	Visual
Thermal Conductivity (W/mK)	5.0	Hot Disk™
Hardness (Shore 00)	66; 3	ASTM D2240
Specific Gravity	1.73	Helium Pycnometer
Thickness Range	0.020" - .200" (0.5 - 5.0mm)	
Thickness Tolerance	±10%	
UL Flammability Rating	94 V0	File E180840
Temperature Range	-45°C to 200°C	See reliability report
Volume Resistivity (ohm-cm)	1×10^{13}	ASTM D257
Outgassing TML	1.0%	ASTM E595
Outgassing CVCM	0.13%	ASTM E595

STANDARD THICKNESSES

Standard thickness 0.020" (0.5mm) through 0.200" (5.0mm) available in 0.010" (0.25mm) increments.

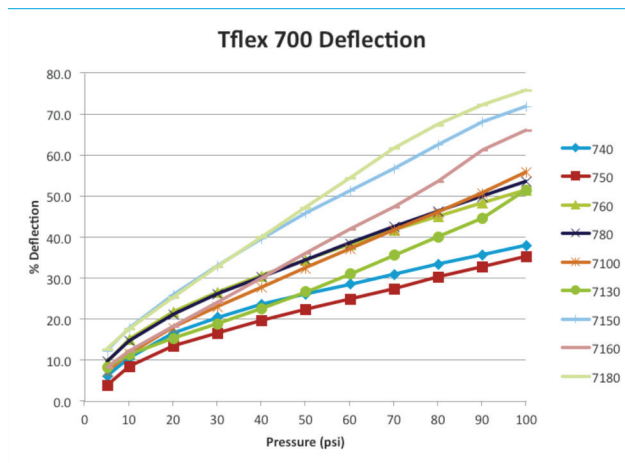
MATERIAL NAME AND THICKNESS

Tflex™ - indicates elastomeric gap filler product line.

7XXX - indicates Tflex™ 700 product line and thickness in mils (0.001-inches).

-DC1 - one side tacky; default is both sides tacky.

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.



THR-DS-TFLEX-700_07_2_14

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